

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Sriram MUTHUKUMAR</td><td>07/09/2007</td></tr><tr><td>Raul MANCERA</td><td>07/09/2007</td></tr><tr><td>Yoshihiro TOMITA</td><td>07/09/2007</td></tr><tr><td>Chi-won HWANG</td><td>07/09/2007</td></tr></tbody></table>		Name	Execution Date	Sriram MUTHUKUMAR	07/09/2007	Raul MANCERA	07/09/2007	Yoshihiro TOMITA	07/09/2007	Chi-won HWANG	07/09/2007
Name	Execution Date										
Sriram MUTHUKUMAR	07/09/2007										
Raul MANCERA	07/09/2007										
Yoshihiro TOMITA	07/09/2007										
Chi-won HWANG	07/09/2007										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>Intel Corporation</td></tr><tr><td>Street Address:</td><td>2200 Mission College Boulevard</td></tr><tr><td>City:</td><td>Santa Clara</td></tr><tr><td>State/Country:</td><td>CALIFORNIA</td></tr><tr><td>Postal Code:</td><td>95052</td></tr></table>		Name:	Intel Corporation	Street Address:	2200 Mission College Boulevard	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052
Name:	Intel Corporation										
Street Address:	2200 Mission College Boulevard										
City:	Santa Clara										
State/Country:	CALIFORNIA										
Postal Code:	95052										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11755735</td></tr></tbody></table>		Property Type	Number	Application Number:	11755735						
Property Type	Number										
Application Number:	11755735										
CORRESPONDENCE DATA											
Fax Number: (310)556-7984 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone: 310-556-7983											
Email: gbell@ipmatters.com											
Correspondent Name: Konrad Raynes and Victor LLP											
Address Line 1: 315 S. Beverly Dr.											
Address Line 2: Sutie 210											
Address Line 4: Beverly Hills, CALIFORNIA 90212											
ATTORNEY DOCKET NUMBER:	P25596 (77.200)										
NAME OF SUBMITTER:	Geoffrey Bell										

CH \$40.00 11755735

500871136

PATENT
REEL: 022747 FRAME: 0714

Total Attachments: 4

source=P25596_Assign#page1.tif

source=P25596_Assign#page2.tif

source=P25596_Assign#page3.tif

source=P25596_Assign#page4.tif

Attorney Docket No.: P25596

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Sriram MUTHUKUMAR, Raul MANCERA, Yoshihiro TOMITA, and Chi-won HWANG

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

MULTI-CHIP PACKAGING USING AN INTERPOSER SUCH AS A SILICON BASED INTERPOSER WITH THROUGH-SILICON-VIAS

(I hereby authorize and request my attorney, associated with Customer Number 46915, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on May 30, 2007 as

United States Application Number 11/755,735 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,


and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent

Attorney Docket No.: P25596

protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

CITY DATE	(1) at <u>Chandler</u> on <u>July 9th</u> , 2007	 _____ Sriram MUTHUKUMAR	SIGNATURE INVENTOR
--------------	--	--	-----------------------

CITY DATE	(2) at <u>Chandler</u> on <u>July 9th</u> , 2007	 _____ Raul MANCERA	SIGNATURE INVENTOR
--------------	--	---	-----------------------

CITY DATE	(3) at _____ on _____, 2007	_____ Yoshihiro TOMITA	SIGNATURE INVENTOR
--------------	--------------------------------------	---------------------------	-----------------------

CITY DATE	(4) at _____ on _____, 2007	_____ Chi-won HWANG	SIGNATURE INVENTOR
--------------	--------------------------------------	------------------------	-----------------------

Attorney Docket No.: P25596

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Sriram MUTHUKUMAR, Raul MANCERA, Yoshihiro TOMITA, and Chi-won HWANG

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

MULTI-CHIP PACKAGING USING AN INTERPOSER SUCH AS A SILICON BASED INTERPOSER WITH THROUGH-SILICON-VIAS

(I hereby authorize and request my attorney, associated with Customer Number 46915, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on May 30, 2007 as

United States Application Number 11/755,735 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent

Attorney Docket No.: P25596

protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

CITY DATE	(1) at _____	_____ Sriram MUTHUKUMAR	SIGNATURE INVENTOR
	on _____ 2007		

CITY DATE	(2) at _____	_____ Raul MANCERA	SIGNATURE INVENTOR
	on _____ 2007		

CITY DATE	(3) at <u>Tsukuba (JP)</u>	<u>Yoshihiro Tomita</u> Yoshihiro TOMITA	SIGNATURE INVENTOR
	on <u>July 9</u> 2007		

CITY DATE	(4) at <u>Tsukuba (JP)</u>	<u>Chiwon Hwang</u> Chi-won HWANG	SIGNATURE INVENTOR
	on <u>July 9</u> 2007		